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AMIS-30660 - Power Dissipation in Case of Bus Failure



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APPLICATION NOTE

Introduction

The AMIS–30660 high speed CAN transceiver is designed to withstand bus failures. Without any damage to the IC the CANH or CANL line may be shorted to ground, V_{CC} or the battery supply. However in some bus failure conditions an increase in power dissipation might occur. This will lead to a rise in junction temperature.

Two bus states can be distinguished: recessive and dominant. In both states both CANH and CANL can be shorted to GND, V_{CC} or V_{BAT} . In this application note we are investigating the worst case conditions therefore short to V_{CC} is not discussed.

Recessive State

In the recessive state TxD = 1 and both CANH and CANL drivers are disabled. Figure 1 illustrates the equivalent schematic. R_{BUS} is the total impedance of the (split) termination on both end–sides of the CAN bus. The typical value is 60 Ω . $R_{i,cm}$ is the common mode input impedance with a typical value of 25 k Ω . V_{CC} is the 5 V supply. Without power ($V_{CC} = 0$ V) the common mode voltage is still kept by a passive clamp but can be higher than $V_{CC}/2$. This particular condition is not taken into account in the calculations.

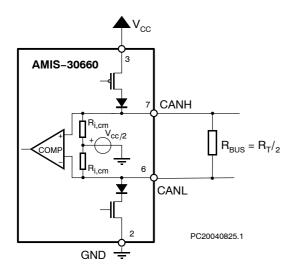


Figure 1. Equivalent Schematic in Recessive State

The power dissipation for the different bus-error conditions is given in Table 1.

Table 1. POWER DISSIPATION FOR CAN-BUS ERRORS IN RECESSIVE STATE

	Short To	
Bus	GND	V _{BAT}
CANL	$P\approx\frac{V_{CC}^{2}}{2R_{i,cm}}$	$P \approx \frac{2 \! \left(V_{BAT} - V_{CC} / 2 \right)^2}{2R_{i,cm}}$
CANH	$P\approx\frac{V_{CC}^{2}}{2R_{i,cm}}$	$P \approx \frac{2 \! \left(V_{BAT} - V_{CC} / 2 \right)^2}{2 R_{i,cm}}$

Calculated for V_{CC} = 5 V, V_{BAT} = 24 V, $R_{i,cm}$. = 25 k Ω and R_{BUS} << $R_{i,cm}$ yields in:

Table 2. CALCULATED POWER DISSIPATION FOR
CAN-BUS ERRORS IN RECESSIVE STATE

	Short To	
Bus	GND	V _{BAT}
CANL	0.5 mW	37 mW
CANH	0.5 mW	37 mW

Dominant State

In dominant state TxD = 0 and both drivers are active. In case of a short circuit the currents for both CANH and CANL are limited to $I_{o(sc)}$ which is 120 mA in worst case condition. Figure 2 illustrates the equivalent schematic.

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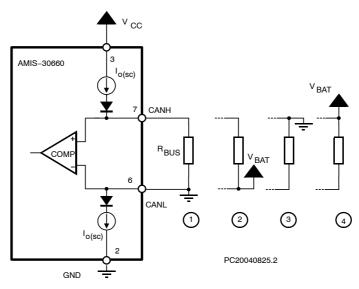


Figure 2. Equivalent Schematic in Dominant State

The power dissipation for the different bus-error conditions is given in Table 3.

Table 3. POWER DISSIPATION FOR	CAN-BUS ERRORS IN DOMINANT STATE

	Short To		
Bus	GND	V _{BAT}	
CANL	See Figure 2 Case (1) Bus Communication Possible but with Bit Timing Limitations	See Figure 2 Case (2) Both CANL/CANH are on V_{BAT} Level through $R_{BUS} \rightarrow$ No Communication Possible Time–Out by Master	
	$P = \frac{(V_{CC} - V_{O(dom)CANH})^2}{R_{BUS}}$	$P = V_{BAT} \cdot I_{O(sc)}$	
CANH	See Figure 2 Case (3) Both CANL/CANH are on GND Level through $R_{BUS} \rightarrow$ No Communication Possible Time-Out by Master	See Figure 2 Case (4) Bus Communication Possible but with Bit Timing Limita- tions	
	$P = V_{CC} \cdot I_{O(sc)}$	$P = V_{BAT} \cdot I_{O(sc)} - R_{BUS} \cdot I_{O(sc)}^{2}$	

Calculated for V_{CC} = 5 V, V_{BAT} = 24 V, R_{BUS} = 60 Ω , $I_{o(SC)}$ = 120 mA and $V_{o(dom)CANH}$ = 3.6 V yields in:

Table 4. CALCULATED POWER DISSIPATION FOR CAN-BUS ERRORS IN DOMINANT STATE

	Short To	
Bus	GND	V _{BAT}
CANL	108 mW	2.88 W (Note 1)
CANH	350 mW	2.02 W

 Because no communication is possible, the master (depending on the application software) will cease the communication (= permanent recessive state) and the dissipated power drops to 37 mW.

Average Power Dissipation and Related Increase in Junction Temperature

The worst case condition from application point of view is a short to V_{BAT} on the CANH Pin in dominant state. Communication is still possible but the dissipation is 2.02 W giving the boundary conditions as stipulated in .

Calculating with a duty cycle of 50% (meaning 50% of the transmission time the bus is in dominant state) the average power dissipation is 1.01 W (neglecting the 37 mW dissipation in recessive state).

The thermal resistance of the package is 150 K/W in free–air. Soldered on a two layer PCB $R_{th(vj-a)} < 100$ K/W is expected. Calculating with 100 K/W yields in a worst case expected temperature increase of 101°C.

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